



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-01-18
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	GIUSEPPE VITALI PALMA	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	KK07*U364BIZ	A	SH1A	2013-01-18
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used on	ium/Gold (Ni/Pd/Au) Tin/Bismuth (S	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	3	gull wing	
Comment	PACKAGE: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	KKO7*U364BIZ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	3.599	mg	supplier	die	Silicon (Si)	7440-21-3		3.52	mg	978049	46140
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1389	66
				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.023	mg	6391	301
						Silicon Oxide(SiO2)	7631-86-9		0.031	mg	8614	406
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.002	mg	556	26
Leadframe	Copper & its alloys	31.649	mg	supplier	alloy	Nickel (Ni)	7440-02-0		0.018	mg	5001	236
						Copper (Cu)	7440-50-8		31.56	mg	997188	413685
						Iron (Fe)	7439-89-6		0.015	mg	474	197
						Iron Phosphide (FeP)	26508-33-8		0.027	mg	853	354
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1390	577
						Palladium (Pd)	7440-05-3		0.001	mg	32	13
						Gold (Au)	7440-57-5		0.001	mg	32	13
Die attach	Other Organic Materials	1.147	mg	supplier	glue	Silver (Ag)	7440-22-4		0.001	mg	32	13
						Silver (Ag)	7440-22-4		1.044	mg	910201	13685
						acrylate	Proprietary		0.057	mg	49695	747
Bonding wire	Other inorganic materials	0.054	mg	supplier	wire	Methacrylate	Proprietary		0.046	mg	40105	603
						Copper (Cu)	7440-50-8		0.054	mg	1000000	708
						Phenol Resin	Proprietary		1.992	mg	49999	26111
						Silica, vitreous	60676-86-0		34.503	mg	866017	452261
encapsulation	Other Organic Materials	39.841	mg	supplier	mold compound	Carbon black	1333-86-4		0.199	mg	4995	2608
						Epoxy Resin	Proprietary		2.988	mg	74998	39166
						Bismuth (Bi)	7440-69-9		0.159	mg	3991	2084